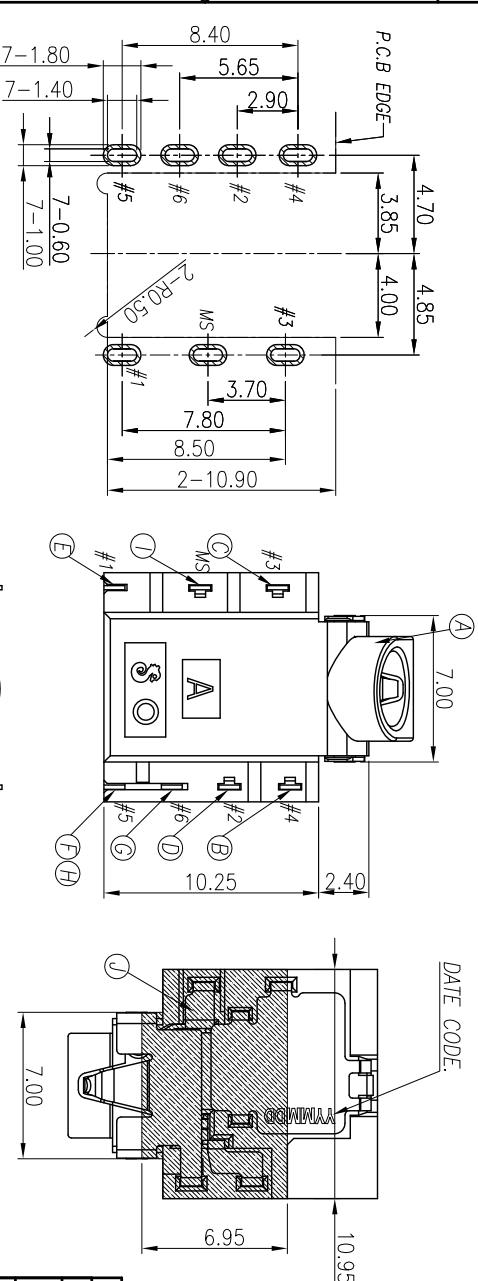
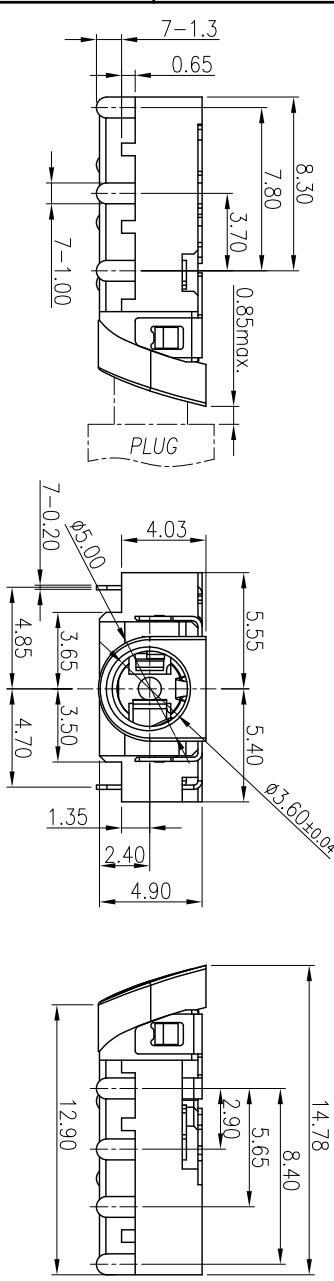
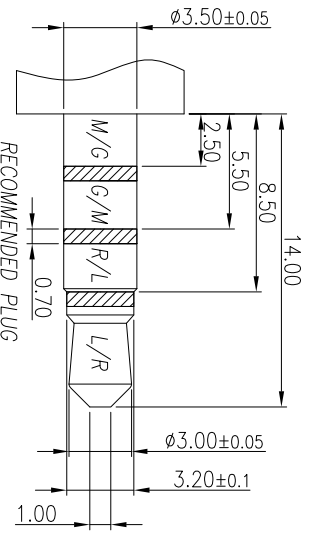


REV./ECN NO OR PDR NO.:	DESCRIPTION	REVISED	DATE
A	PDR NO.: T140502-2A	Kevin	2014.08.21

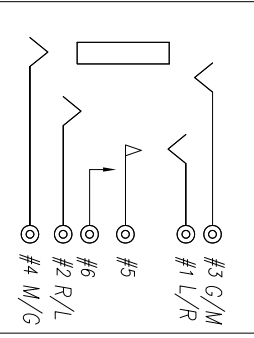


RECOMMENDED PCB LAYOUT
TOP VIEW; T=1.2mm; TOL. ±0.05



Ø3.5 4-POLE STANDARD PLUG

SCHEMATIC



- SPECIFICATIONS:**
- ELECTRICAL CHARACTERISTICS:**
 - 1-1. RATING: 12V 1A
 - 1-2. CONTACT RESISTANCE: 50mΩ MAX (INITIAL)
 - 1-3. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
 - 1-4. INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500V DC
 - MECHANICAL CHARACTERISTICS:**
 - 2-1. INSERTION FORCE : 0.3~3.0 KGF
 - 2-2. WITHDRAWAL FORCE : 0.3~3.0 KGF
 - LIFE TEST: 5,000 CYCLES MIN.**
 - OTHER GENERAL SPEC. TO REFER "2SJ3095 SERIES SPEC".**
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.**
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:**
 - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:**
 - FOR REFLOW SOLDERING LEAD-FREE PROCESS.**



J	MYLAR	1	CAPTON, 0.06t	YELLOW
I	SHELL	1	COPPER ALLOY, 0.2t	Ni 80U 3Min.
H	SEPARATOR	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
G	MAKE-TERMINAL	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA GOLD FLASH ON SOLDER AREA ALL OVER 50U" Ni.
F	TRANSFER-TERMINAL	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA GOLD FLASH ON SOLDER AREA ALL OVER 50U" Ni.
E	TIP-SPRING	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA GOLD FLASH ON SOLDER AREA ALL OVER 50U" Ni.
D	RING-A	1	COPPER ALLOY, 0.2t	ALL OVER 50U" Ni.
C	RING-B	1	COPPER ALLOY, 0.2t	ALL OVER 50U" Ni.
B	EARTH	1	COPPER ALLOY, 0.2t	ALL OVER 50U" Ni.
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES:

DECIMALS: ANGLES:

X : ±0.5 X : ±2°
X.X : ±0.3 X.X : ±1°
X.XX : ±0.2

信晋企业股份有限公司
Singatron Enterprise Co., Ltd.

3.5Ø PHONE JACK

PART NO. 2SJ3095-04111F

SCALE 4:1 UNIT: mm

SIZE: A3 SHEET: 1 OF 1 REV: A

CUSTOMER COPY